10A, 100V Schottky Barrier Surface Mount Rectifier

FEATURES

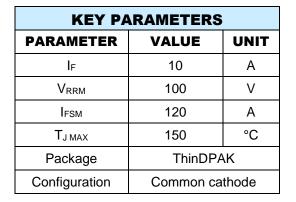
- AEC-Q101 qualified
- Low power loss, high efficiency
- Ideal for automated placement
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

APPLICATIONS

- Low voltage, high frequency, inverter
- DC/DC converter
- Freewheeling diodes
- Reverse battery protection
- Car lighting

MECHANICAL DATA

- Case: ThinDPAK
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.196g (approximately)

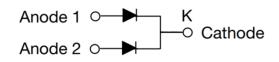


S 1 2 K

ROHS HALOGEN

Th'nDPAK®

ThinDPAK



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)				
PARAMETER		SYMBOL	MBRAD10100DH	UNIT
Marking code on the device			10100D	
Repetitive peak reverse voltage		V _{RRM}	100	V
Reverse voltage, total rms value		V _{R(RMS)}	70	V
Forward current per device		lF	10	Α
Surge peak forward current single half sine wave superimposed on rated load per diode	t = 8.3ms	IFSM	120	А
	t = 1.0ms		260	Α
Junction temperature		TJ	-55 to +150	°C
Storage temperature		Tstg	-55 to +150	°C





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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	ТҮР	UNIT
Junction-to-lead thermal resistance ⁽¹⁾	R _{ejl}	1.8	°C/W
Junction-to-ambient thermal resistance ⁽²⁾	Reja	12.1	°C/W
Junction-to-case thermal resistance ⁽²⁾	Rejc	3.7	°C/W

Notes:

1. With ideal heat sink

2. Units mounted on 2" x 3" x 0.25" Al-plate

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage per diode ⁽¹⁾	$I_F = 2.5A, T_J = 25^{\circ}C$	VF	0.71	-	V
	$I_F = 5.0A, T_J = 25^{\circ}C$		0.77	0.85	V
	I _F = 2.5A, T _J = 125°C		0.56	-	V
	$I_F = 5.0A, T_J = 125^{\circ}C$		0.63	0.70	V
Reverse current @ rated V_R per diode ⁽²⁾	$T_J = 25^{\circ}C$	I _R	-	10	μA
	T _J = 125°C		-	1	mA
Junction capacitance per diode	$1MHz, V_R = 4.0V$	CJ	94	-	pF

Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
MBRAD10100DH	ThinDPAK	4,500 / Tape & Reel	



10000

1000

100

10

1 0.1

0.01

0.001

10

20

30

40

NSTANTANEOUS REVERSE CURRENT (µA)

CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

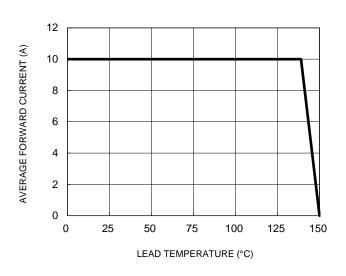


Fig.1 Forward Current Derating Curve

Fig.3 Typical Reverse Characteristics

T_J=150°C

T_=125°C

T_{.1}=25°C

PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

60

70

50

Fig.2 Typical Junction Capacitance

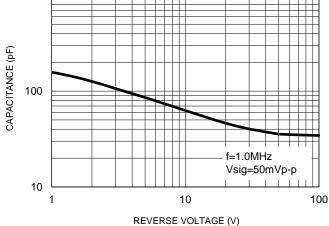
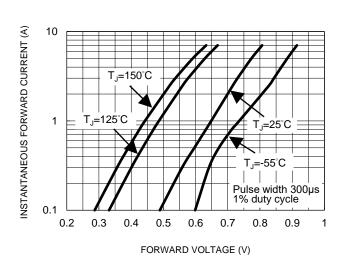
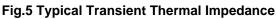


Fig.4 Typical Forward Characteristics



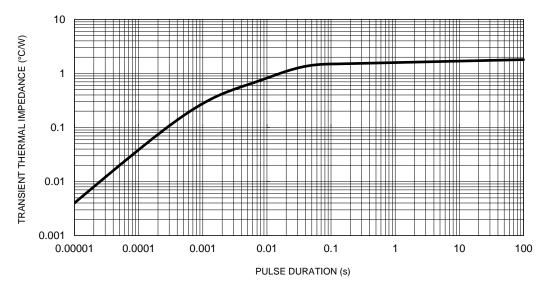


100

90

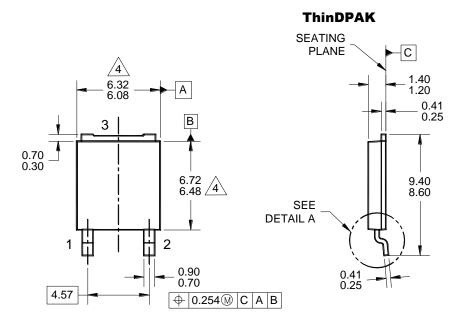
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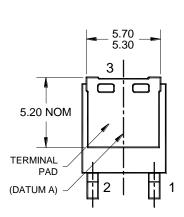
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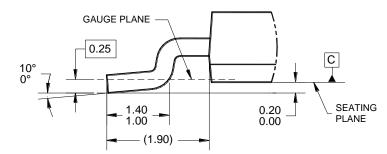




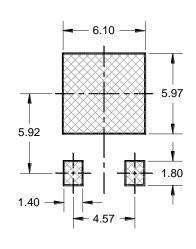
PACKAGE OUTLINE DIMENSIONS



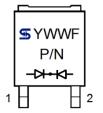




DETAIL A, ROTATED -90° (SCALE 4:1)



SUGGESTED PAD LAYOUT



MARKING DIAGRAM

YWW	= DATE CODE
F	= FACTORY CODE
P/N	= MARKING CODE

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC TO-252, VARIATION AE, ISSUE F.
- 4 MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSION, OR GATE BURRS.
- 5. DWG NO. REF: HQ2SD07-TDPAK-065 REV A.



MBRAD10100DH

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